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Industry

Drive Technologies

For the trade press

Nuremberg, June 3, 2008

SMT Hybrid Packaging 2008

Siplace delivers more flexibility and quality to European electronics manufacturers

Siemens will present its portfolio, which is designed for the needs of European electronics manufacturers, at this year's SMT Hybrid Packaging Trade Show in Nuremberg. Highlights will be the Siplace X4i, which is the company's top model and the fastest 4-gantry placement solution in the market. In addition, Siemens will also exhibit the powerful and cost-effective machines of the Siplace D-Series, demonstrating their high placement quality and flexibility for small and intermediate lot sizes. Furthermore, the experts of the Siplace team will show how their software and services enable manufacturers to achieve non-stop product changeovers, zero-dpm (defects per million) quality and the fastest new product introductions. Using Siplace's unique 'Compare' Checklists, visitors to the SMT show will be able to compare all relevant performance aspects with solutions that are offered by other manufacturers.

With its Siplace X4i, Siemens will present the absolute world record holder in placement performance at this year's SMT show in Nuremberg. The machine is capable of placing more than 102,000 components per hour (cph) in accordance with the international IPC standard. This corresponds to 120,000 cph based on the Siplace benchmark test and a theoretical placement speed of 135,000 cph. What is important for European electronics manufacturers: The Siplace X4i combines this performance with high flexibility thanks to its synchronous or asynchronous dual-lane transport and its intelligent X-type component feeders, as well as its innovative Productivity Lane and i-Placement features.

For electronics manufacturers in the mid-sized market segment, the Siplace D-Series offers an outstanding price-performance ratio along with high quality. For example, the D-platform features the same digital vision system as the high-end X-Series machines. The D-Series machines are capable of processing the complete component spectrum down to the super-small 01005 components of the next generation efficiently and with maximum placement accuracy.

Another highlight of Siemens's show presentation is the Siplace 'Compare' initiative, which provides electronics manufacturers with valuable help when it comes to making far-reaching investment decisions. Using Siplace's unique 'Compare' checklists, electronics manufacturers can prepare objective comparisons of the performance and cost aspects of various solution providers. The checklists ensure that all major investment decision aspects, based on IPC Standards, will be taken into account.

At the SMT Show in Nuremberg, Electronics manufacturers will see first hand how easy the Siplace Vision Teaching Station makes it to describe components of new products quickly and easily, as well as generating and optimizing placement programs offline without having to interrupt the production lines. In combination with Siplace Calibration Services, the Siplace Vision Teaching Station makes it possible to achieve zero-dpm process quality right from the start. In the Software section, Siemens will show in a live presentation how the Siplace LES software maximizes line productivity with non-stop setup changeovers even for small lot sizes.

In the Services section Siplace gives insight into the broad spectrum of Siplace services, which ranges from Traceability concepts and Calibration Services to Feeder Care and customer-specific and success-oriented All-Included Packages.

More Information about Siplace at: www.siplace.com

You find the press release at: www.siemens.com/automation/press

A picture accompanies this press release. You can find this picture on the Internet at: www.siemens.com/ad-picture/1684



The Siplace X4i, currently the fastest 4-gantry placement solution worldwide, as well as the high-performance and cost-effective D-series machines demonstrate their high quality and enormous flexibility for small and medium batch sizes at the SMT Hybrid Packaging 2008.

You find the picture for the press release at: www.siemens.com/ad-pictures/1684

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